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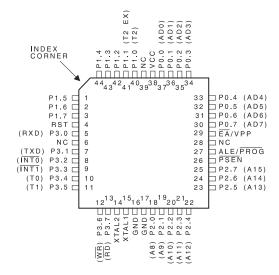
Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	12MHz
Connectivity	UART/USART
Peripherals	-
Number of I/O	32
Program Memory Size	20KB (20K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89lv55-12ac

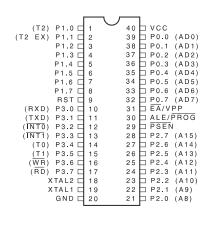


2. Pin Configurations

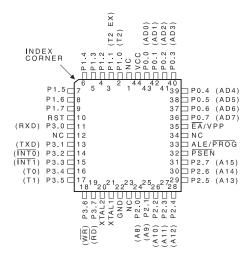
2.1 44A - 44-lead TQFP



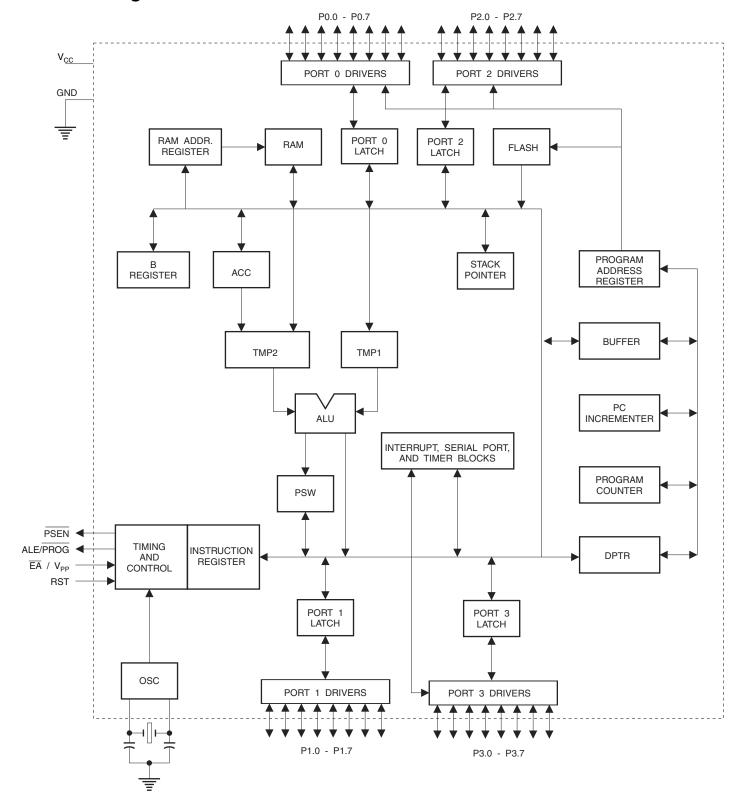
2.2 40P6 - 40-lead PDIP



2.3 44J – 44-lead PLCC



3. Block Diagram





4.6 Port 3

Port 3 is an 8-bit bi-directional I/O port with internal pullups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{II}) because of the pullups.

Port 3 also serves the functions of various special features of the AT89LV55, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	ĪNTŌ (external interrupt 0)
P3.3	ĪNT1 (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	WR (external data memory write strobe)
P3.7	RD (external data memory read strobe)

Port 3 also receives the highest-order address bit and some control signals for Flash programming and verification.

4.7 RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

4.8 ALE/PROG

Address Latch Enable is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input (PROG) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

4.9 PSEN

Program Store Enable is the read strobe to external program memory.

When the AT89LV55 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory.





6. Data Memory

The AT89LV55 implements 256 bytes of on-chip RAM. The upper 128 bytes occupy a parallel address space to the Special Function Registers. That means the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions that use direct addressing access SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

```
MOV 0A0H, #data
```

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

```
MOV @RO, #data
```

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

Timer 0 and 1

Timer 0 and Timer 1 in the AT89LV55 operate the same way as Timer 0 and Timer 1 in the AT89C51. For further information on the timers' operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF

8. Timer 2

Timer 2 is a 16-bit Timer/Counter that can operate as either a timer or an event counter. The type of operation is selected by bit $C/\overline{T2}$ in the SFR T2CON (shown in Table 5-2). Timer 2 has three operating modes: capture, auto-reload (up or down counting), and baud rate generator. The modes are selected by bits in T2CON, as shown in Table 8-1.

Timer 2 consists of two 8-bit registers, TH2 and TL2. In the Timer function, the TL2 register is incremented every machine cycle. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

In the Counter function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected. Since two machine cycles (24 oscillator periods) are required to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. To ensure that a given level is sampled at least once before it changes, the level should be held for at least one full machine cycle.

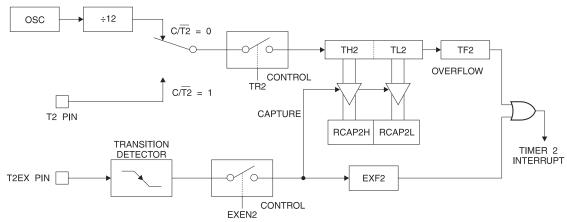
Table 8-1. Timer 2 Operating Modes

RCLK + TCLK	CP/RL2	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud Rate Generator
X	Х	0	(Off)

8.1 Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 8-1.

Figure 8-1. Timer 2 in Capture Mode



8.2 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 8-2). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Figure 8-2 shows Timer 2 automatically counting up when DCEN = 0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in RCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 8-3. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.





A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.

Figure 8-2. Timer 2 Auto Reload Mode (DCEN = 0)

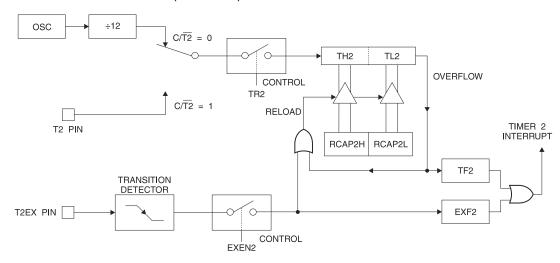


 Table 8-2.
 T2MOD—Timer 2 Mode Control Register

T2MC	T2MOD Address = 0C9H Reset Value = XXXX XX00B							
Not Bit Addressable								
	-	_	-	_	_	_	T20E	DCEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
_	Not implemented, reserved for future use.
T20E	Timer 2 Output Enable bit.
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter.



9. Baud Rate Generator

Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (Table 5-2). Note that the baud rates for transmit and receive can be different if Timer 2 is used for the receiver or transmitter and Timer 1 is used for the other function. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode, as shown in Figure 8-4.

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate according to the following equation.

The Timer can be configured for either timer or counter operation. In most applications, it is configured for timer operation ($CP/\overline{T2}=0$). The timer operation is different for Timer 2 when it is used as a baud rate generator. Normally, as a timer, it increments every machine cycle (at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (at 1/2 the oscillator frequency). The baud rate formula is given below.

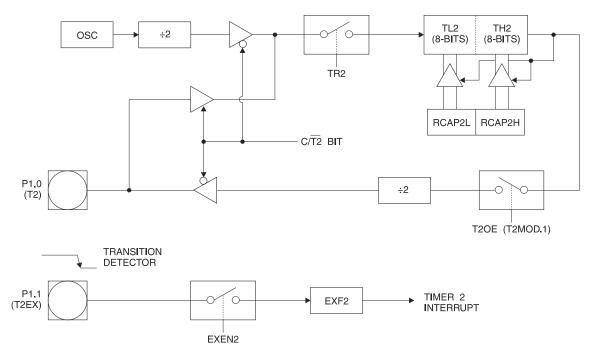
$$\frac{\text{Modes 1 and 3}}{\text{Baud Rate}} = \frac{\text{Oscillator Frequency}}{32 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

Timer 2 as a baud rate generator is shown in Figure 8-4. This figure is valid only if RCLK or TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2 and will not generate an interrupt. Note too, that if EXEN2 is set, a I-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt.

Note that when Timer 2 is running (TR2 = 1) as a timer in the baud rate generator mode, TH2 or TL2 should not be read from or written to. Under these conditions, the Timer is incremented every state time, and the results of a read or write may not be accurate. The RCAP2 registers may be read but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

Figure 9-1. Timer 2 in Clock-out Mode



10. Programmable Clock Out

A 50% duty cycle clock can be programmed to come out on P1.0, as shown in Figure 9-1. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed to input the external clock for Timer/Counter 2 or to output a 50% duty cycle clock ranging from 61 Hz to 3 MHz at a 12 MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit $C/\overline{T2}$ (T2CON.1) must be cleared and bit T2OE (T2MOD.1) must be set. Bit TR2 (T2CON.2) starts and stops the timer.

The clock-out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, TCAP2L), as shown in the following equation:

$$\label{eq:clock-out} \text{Clock-Out Frequency} = \frac{\text{Oscillator Frequency}}{4 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

In the clock-out mode, Timer 2 roll-overs will not generate an interrupt. This behavior is similar to when Timer 2 is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and clock-out frequencies cannot be determined independently from one another since they both use RCAP2H and RCAP2L.

11. UART

The UART in the AT89LV55 operates the same way as the UART in the AT89C51. For further information on the UART operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF



12. Interrupts

The AT89LV55 has a total of six interrupt vectors: two external interrupts (INT0 and INT1), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 12-1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 12-1 shows that bit position IE.6 is unimplemented. In the AT89C51 and AT89LV51, bit position IE.5 is also unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows. For further information, see the Microcontroller Data Book, section titled "Interrupts."

Table 12-1. Interrupt Enable (IE) Register

(MSI	3)							((LSB)
	EA	_	ET2	ES	ET1	EX1	ET0	EX0	
	Cookle Dit 1			1	1		1		

Enable Bit = 1 enables the interrupt.

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
_	IE.6	Reserved.
ET2	IE.5	Timer 2 interrupt enable bit.
ES	IE.4	Serial Port interrupt enable bit.
ET1	IE.3	Timer 1 interrupt enable bit.
EX1	IE.2	External interrupt 1 enable bit.
ET0	IE.1	Timer 0 interrupt enable bit.
EX0	IE.0	External interrupt 0 enable bit.
User software should	never write 1s to unimp	lemented bits, because they may be used in future AT89 products.

16. Program Memory Lock Bits

The AT89LV55 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in Table 16-1:

Table 16-1. Lock Bit Protection Modes

ı	Program	Lock Bits	5		
	LB1	LB2	LB3	Protection Type	
1	U	U	U	No program lock features.	
2	Р	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset, and further programming of the Flash memory is disabled.	
3	Р	Р	U	Same as mode 2, but verify is also disabled.	
4	Р	Р	Р	Same as mode 3, but external execution is also disabled.	

When lock bit 1 is programmed, the logic level at the \overline{EA} pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of \overline{EA} must agree with the current logic level at that pin in order for the device to function properly.

The AT89LV55 code memory array is programmed byte-by-byte. To program any non-blank byte in the on-chip Flash Memory, the entire memory must be erased using the Chip Erase Mode.

17. Programming the Flash

The AT89LV55 is normally shipped with the on-chip Flash memory array in the erased state (that is, contents = FFH) and ready to be programmed.

Programming Algorithm: Before programming the AT89LV55, the address, data and control signals should be set up according to Table 18-1, "Flash Programming Modes," on page 19 and Figure 18-1. To program the AT89LV55, take the following steps:

- 1. Input the desired memory location on the address lines.
- 2. Input the appropriate data byte on the data lines.
- 3. Activate the correct combination of control signals.
- 4. Raise EA/V_{PP} to 12V
- 5. Pulse ALE/PROG once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 1.5 ms. Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

Data Polling: The AT89LV55 features Data Polling to indicate the end of a write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on PO.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. Data Polling may begin any time after a write cycle has been initiated.

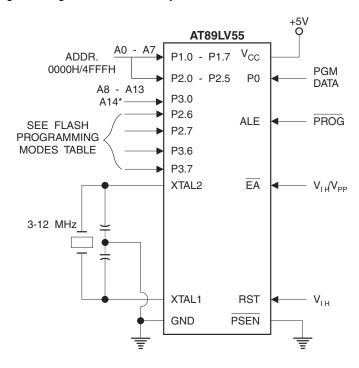
Ready/Busy: The progress of byte programming can also be monitored by the RDY/BUSY output signal. P3.4 is pulled low after ALE goes high during programming to indicate BUSY. P3.4 is pulled high again when programming is done to indicate READY.





Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. The lock bits cannot be verified directly. Verification of the lock bits is achieved by observing that their features are enabled.

Figure 17-1. Programming the Flash Memory



*Programming address line A14 (P3.0) is not the same as the external memory address line A14 (P2.6)

Chip Erase: The entire Flash array is erased electrically by using the proper combination of control signals and by holding ALE/PROG low for 10 ms. The code array is written with all 1s. The chip erase operation must be executed before the code memory can be reprogrammed.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H, and 031H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows:

(030H) = 1EH indicates manufactured by Atmel

(031H) = 65H indicates 89LV55

(032H) = FFH indicates 12V programming

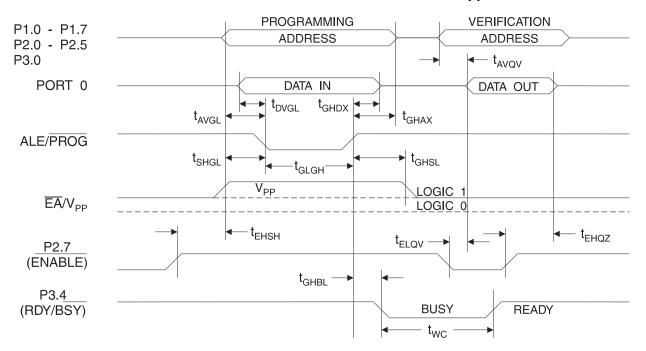


19. Flash Programming and Verification Characteristics

 $T_A = 0^{\circ} C$ to $70^{\circ} C$, $V_{CC} = 5.0 V \pm 10\%$

Symbol	Parameter	Min	Max	Units
V _{PP}	Programming Enable Voltage	11.5	12.5	V
I _{PP}	Programming Enable Current		1.0	mA
1/t _{CLCL}	Oscillator Frequency	3	12	MHz
t _{AVGL}	Address Setup to PROG Low	48t _{CLCL}		
t _{GHAX}	Address Hold After PROG	48t _{CLCL}		
t _{DVGL}	Data Setup to PROG Low	48t _{CLCL}		
t _{GHDX}	Data Hold After PROG	48t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) High to V _{PP}	48t _{CLCL}		
t _{SHGL}	V _{PP} Setup to PROG Low	10		μs
t _{GHSL}	V _{PP} Hold After PROG	10		μs
t _{GLGH}	PROG Width	1	110	μs
t _{AVQV}	Address to Data Valid		48t _{CLCL}	
t _{ELQV}	ENABLE Low to Data Valid		48t _{CLCL}	
t _{EHQZ}	Data Float After ENABLE	0	48t _{CLCL}	
t _{GHBL}	PROG High to BUSY Low		1.0	μs
t _{wc}	Byte Write Cycle Time		2.0	ms

20. Flash Programming and Verification Waveforms ($V_{PP} = 12V$)



21. Absolute Maximum Ratings*

Operating Temperature	55°C to +125°C
Storage Temperature	65°C to +150°C
Voltage on Any Pin with Respect to Ground	1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

22. DC Characteristics

The values shown in this table are valid for $T_A = -40^{\circ}\text{C}$ to 85°C and $V_{CC} = 2.7\text{V}$ to 6.0V, unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units
V _{IL}	Input Low Voltage	(Except EA)	-0.5	0.2 V _{CC} - 0.1	V
V _{IL1}	Input Low Voltage (EA)		-0.5	0.2 V _{CC} - 0.3	V
V _{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V _{CC} + 0.9	V _{CC} + 0.5	V
V _{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V _{CC}	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage (1) (Ports 1, 2, 3)	I _{OL} = 1.6 mA		0.45	V
V _{OL1}	Output Low Voltage (1) (Port 0, ALE, PSEN)	I _{OL} = 3.2 mA		0.45	٧
		$I_{OH} = -60 \mu A, V_{CC} = 5V \pm 10\%$	2.4		V
V_{OH}	Output High Voltage (Ports 1, 2, 3, ALE, PSEN)	I _{OH} = -25 μA	0.75 V _{CC}		V
	(1010 1, 2, 0, ALL, 10LN)	I _{OH} = -10 μA	0.9 V _{CC}	0.2 V _{CC} - 0.1 0.2 V _{CC} - 0.3 V _{CC} + 0.5 V _{CC} + 0.5 0.45 0.45 -50 -650 ±10 300 10 25 6.5 100	V
		$I_{OH} = -800 \mu\text{A}, V_{CC} = 5V \pm 10\%$	2.4		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I _{OH} = -300 μA	0.75 V _{CC}		V
	(Fort our External Bas Meas)	$I_{OH} = -80 \mu A$	0.9 V _{CC}	0.2 V _{CC} - 0.3 V _{CC} + 0.5 V _{CC} + 0.5 0.45 0.45 -50 -650 ±10 300 10 25 6.5	V
I _{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V _{IN} = 0.45V		-50	μА
I _{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, 3)	V _{IN} = 2V		-650	μА
I _{LI}	Input Leakage Current (Port 0, EA)	0.45 < V _{IN} < V _{CC}		±10	μА
RRST	Reset Pulldown Resistor		50	300	kΩ
C _{IO}	Pin Capacitance	Test Freq. = 1 MHz, T _A = 25°C		10	pF
	Power Supply Current	Active Mode, 12 MHz		25	mA
	rower Supply Current	Idle Mode, 12 MHz		6.5	mA
I _{cc}	Power-down Mode (1)	V _{CC} = 6V		100	μΑ
	i ower-down wode . /	$V_{CC} = 3V$		40	μΑ

Notes: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:

Maximum I_{OL} per port pin: 10 mA

Maximum I_{OL} per 8-bit port:

Port 0: 26 mA, Ports 1, 2, 3: 15 mA

Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

2. Minimum V_{CC} for Power-down is 2V.





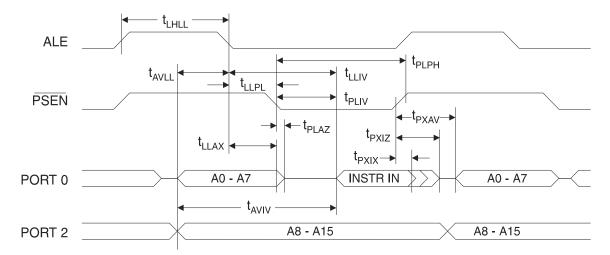
23. AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/ \overline{PROG} , and \overline{PSEN} = 100 pF; load capacitance for all other outputs = 80 pF.

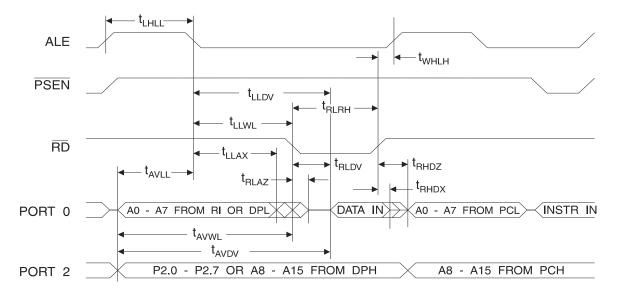
23.1 External Program and Data Memory Characteristics

		12 MHz (Oscillator	Variable	Units		
Symbol	Parameter	Min	Max	Min	Max		
1/t _{CLCL}	Oscillator Frequency			0	12	MHz	
t _{LHLL}	ALE Pulse Width	127		2t _{CLCL} - 40		ns	
t _{AVLL}	Address Valid to ALE Low	43		t _{CLCL} - 40		ns	
t _{LLAX}	Address Hold After ALE Low	48		t _{CLCL} - 35		ns	
t _{LLIV}	ALE Low to Valid Instruction In		233		4t _{CLCL} - 100	ns	
t _{LLPL}	ALE Low to PSEN Low	43		t _{CLCL} - 40		ns	
t _{PLPH}	PSEN Pulse Width	205		3t _{CLCL} - 45		ns	
t _{PLIV}	PSEN Low to Valid Instruction In		145		3t _{CLCL} - 105	ns	
t _{PXIX}	Input Instruction Hold After PSEN	0		0		ns	
t _{PXIZ}	Input Instruction Float After PSEN		59		t _{CLCL} - 25	ns	
t _{PXAV}	PSEN to Address Valid	75		t _{CLCL} - 8		ns	
t _{AVIV}	Address to Valid Instruction In		312		5t _{CLCL} - 105	ns	
t _{PLAZ}	PSEN Low to Address Float		10		10	ns	
t _{RLRH}	RD Pulse Width	400		6t _{CLCL} - 100		ns	
t _{WLWH}	WR Pulse Width	400		6t _{CLCL} - 100		ns	
t _{RLDV}	RD Low to Valid Data In		252		5t _{CLCL} - 165	ns	
t _{RHDX}	Data Hold After RD	0		0		ns	
t _{RHDZ}	Data Float After RD		97		2t _{CLCL} - 70	ns	
t _{LLDV}	ALE Low to Valid Data In		517		8t _{CLCL} - 150	ns	
t _{AVDV}	Address to Valid Data In		585		9t _{CLCL} - 165	ns	
t _{LLWL}	ALE Low to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	200	300	3t _{CLCL} - 50	3t _{CLCL} + 50	ns	
t _{AVWL}	Address to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	203		4t _{CLCL} - 130		ns	
t _{QVWX}	Data Valid to WR Transition	23		t _{CLCL} - 60		ns	
t _{QVWH}	Data Valid to WR High	433		7t _{CLCL} - 150		ns	
t _{WHQX}	Data Hold After WR	33		t _{CLCL} - 50		ns	
t _{RLAZ}	RD Low to Address Float		0		0	ns	
t _{WHLH}	RD or WR High to ALE High	43	123	t _{CLCL} - 40	t _{CLCL} + 40	ns	

24. External Program Memory Read Cycle

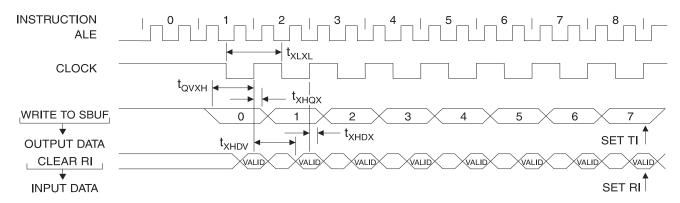


25. External Data Memory Read Cycle

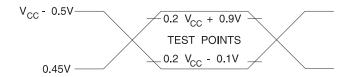




30. Shift Register Mode Timing Waveforms



31. AC Testing Input/Output Waveforms (1)

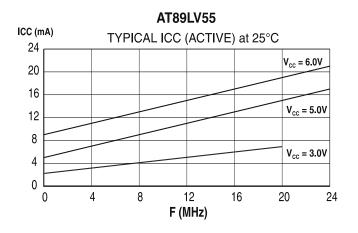


Note: 1. AC Inputs during testing are driven at 2.4V for a logic "1" and 0.45V for a logic "0". Timing measurements are made at 2.0V for a logic "1" and 0.8V for a logic "0".

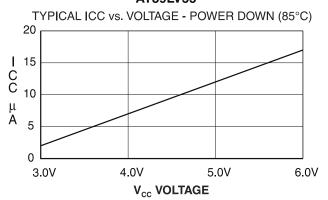
32. Float Waveforms (1)



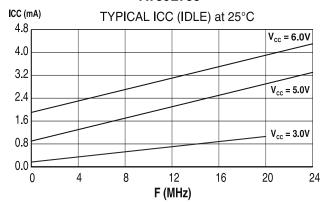
Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.



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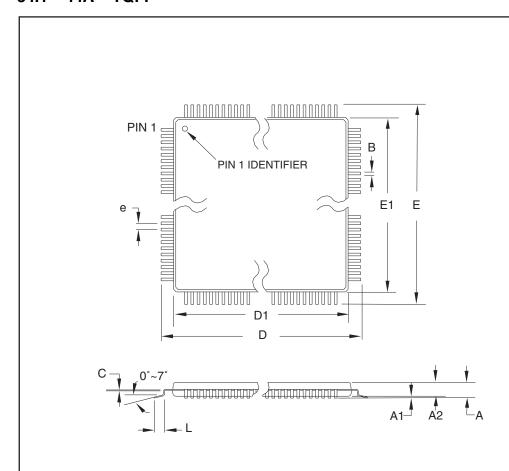
Notes: 1. XTAL1 tied to GND for I_{CC} (power-down)

2. Lock bits programmed



34. Package Information

34.1 44A - TQFP



COMMON DIMENSIONS (Unit of Measure - mm)

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	-	_	1.20	
A1	0.05	_	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
Е	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
В	0.30	-	0.45	
С	0.09	_	0.20	
L	0.45	-	0.75	
е	0.80 TYP			

Notes:

- 1. This package conforms to JEDEC reference MS-026, Variation ACB.
- 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
- 3. Lead coplanarity is 0.10 mm maximum.

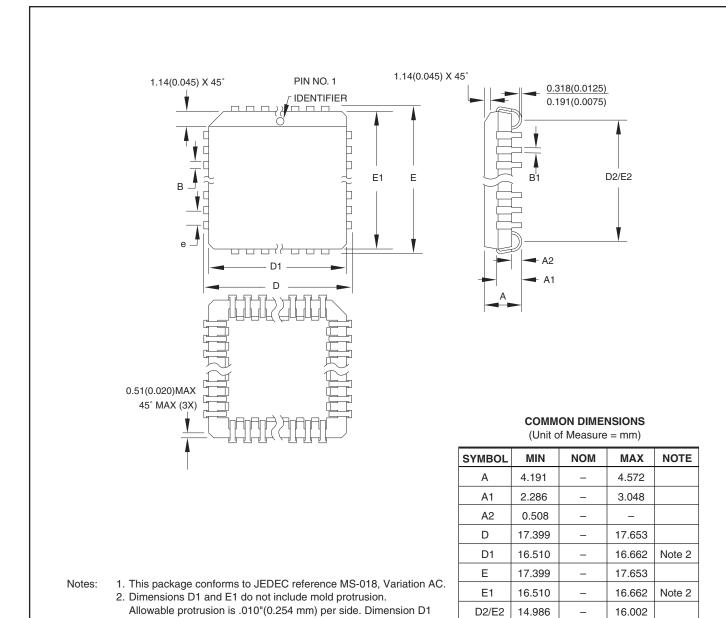
10/5/2001

0005 Ouch and David	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	44A , 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	В





34.2 44J - PLCC



and E1 include mold mismatch and are measured at the extreme

material condition at the upper or lower parting line. 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

0.813

0.533

1.270 TYP

2005.0 1 15 1	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	В

В

В1

е

0.660

0.330



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